

## 200mA Negative Voltage Regulator with ON/OFF Control

## ■ GENERAL DESCRIPTION

The XC6901 Series is a negative voltage CMOS regulator which includes a reference voltage source, error amplifier, driver transistor, current limiter and phase compensator.

The CE function enables the circuit to be in stand-by mode by inputting low level signal. In the stand-by mode, the electric charge at the output capacitor ( $C_L$ ) will be discharged via the internal auto-discharge switch and as a result the  $-V_{OUT}$  pin quickly returns to the  $V_{SS}$  level.

The over current protection circuit will operate when the output current reaches limit current. The thermal shutdown circuit will operate when the junction temperature reaches limit temperature.

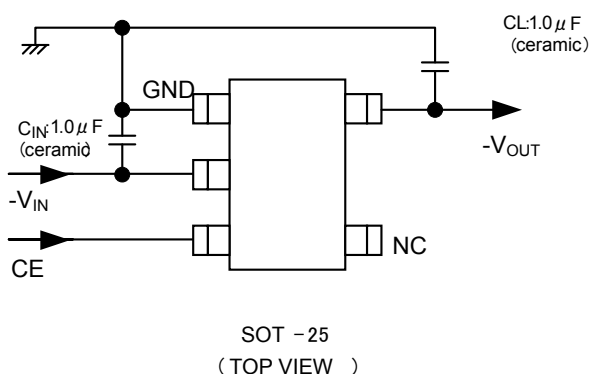
## ■ APPLICATIONS

- CCD power supplies
- LCD Modules
- Op-Amp power supplies
- Digital still cameras
- Battery powered equipment

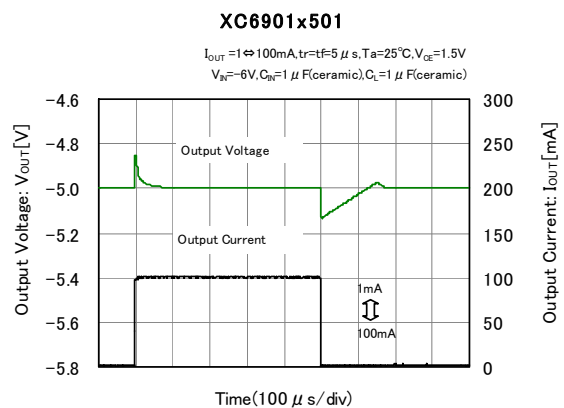
## ■ FEATURES

<b>Maximum Output Current</b>	: 200mA
<b>Input Voltage Range</b>	: -2.4V ~ -12.4V ( $V_{CE}=3.6V$ )
<b>Output Voltage Range</b>	: -0.9V ~ -12.0V
<b>Accuracy</b>	: $\pm 1.5\%$ ( $V_{OUT} < -2.0V$ ) $\pm 0.03V$ ( $V_{OUT} \geq -2.0V$ )
<b>Temperature Stability</b>	: TYP. $\pm 50\text{ppm}/^\circ\text{C}$
<b>CE High Level Voltage</b>	: +1.2V ~ +3.6V, (Active High)
<b>Dropout Voltage</b>	: 400mV @ $I_{OUT}=100\text{mA}$
<b>Low Power Consumption</b>	: 100 $\mu\text{A}$ MAX.
<b>Stand-by Current</b>	: Less than 0.1 $\mu\text{A}$
<b>Protection Circuits</b>	: Current Limit 350mA TYP, Foldback Overheat Protection $T_{TSB}=150^\circ\text{C}$
<b>Output Capacitor</b>	: Ceramic Capacitor Compatible
<b>Built-in Function</b>	: $C_L$ High-Speed Discharge
<b>Operating Ambient Temperature</b>	: $-40^\circ\text{C} \sim +85^\circ\text{C}$
<b>Packages</b>	: SOT-25, SOT-89-5, USP-6C
<b>Environmentally Friendly</b>	: EU RoHS Compliant, Pb Free

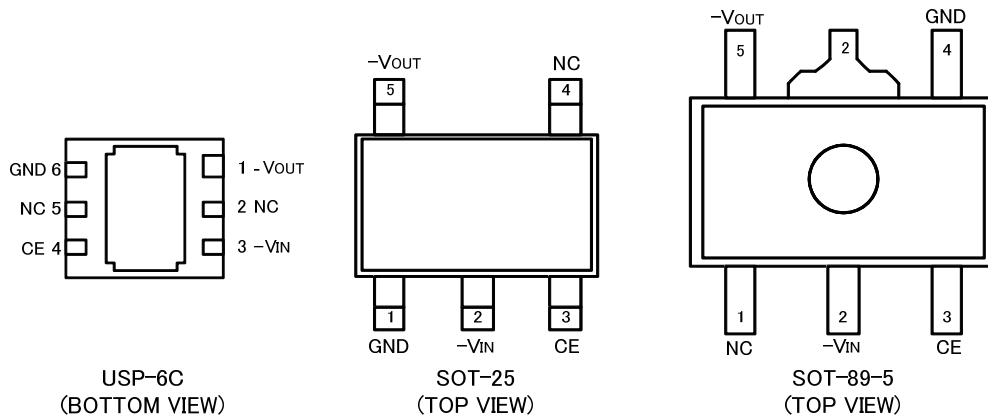
## ■ TYPICAL APPLICATION CIRCUIT



## ■ TYPICAL PERFORMANCE CHARACTERISTICS



## PIN CONFIGURATION



\* The dissipation pad for the USP-6C package should be solder-plated in recommended mount pattern and metal masking to enhance mounting strength and heat release. If the pad needs to be connected to other pins, it should be connected to the -V<sub>IN</sub> (No. 3) pin.

## PIN ASSIGNMENT

PIN NUMBER			PIN NAME	FUNCTIONS
USP-6C	SOT-25	SOT-89-5		
1	5	5	-V <sub>OUT</sub>	Negative Output
2,5	4	1	NC	No Connection
3	2	2	-V <sub>IN</sub>	Negative Supply Input
4	3	3	CE	ON/OFF Control
6	1	4	GND	Ground

## FUNCTION CHART

XC6901 Series D type

PIN NAME	SIGNAL	STATUS
CE	L	Stand-by
	H	Active
	OPEN	Stand-by

## ■ PRODUCT CLASSIFICATION

### ● Ordering Information

XC6901①②③④⑤⑥-⑦<sup>(\*)</sup> ON/OFF Control Voltage Regulator (CE Active High)

DESIGNATOR	ITEM	SYMBOL	DESCRIPTION
①	Type <sup>(2)</sup>	D	CE Pull-down resistor C <sub>L</sub> Auto-discharge
②③	Output Voltage	09~C0	-0.9V~-12V e.g. -0.9V→②=0, ③=9, -12V→②=C, ③=0 A: 10, B: 11, C: 12
④	Output Type	1	0.10V Increments e.g. -1.2V→②=1, ③=2, ④=1
		B	0.05V Increments for -0.95V~-4.95V e.g. -1.25V→②=1, ③=2, ④=B
⑤⑥-⑦	Packages (Order Unit)	ER-G	USP-6C(3,000/Reel)
		MR-G	SOT-25(3,000/Reel)
		PR-G	SOT-89-5 (1,000/Reel)

<sup>(\*)</sup> The "-G" suffix denotes Halogen and Antimony free as well as being fully RoHS compliant.

<sup>(2)</sup> For the type without C<sub>L</sub> auto-discharge, please contact your local Torex sales office or representative.

## ■ STANDARD VOLTAGE

### ● Examples for standard voltage

V <sub>OUT</sub> (V)	PACKAGES		
	USP-6C	SOT-25	SOT-89-5
-1.2V	XC6901D121ER-G	XC6901D121MR-G	XC6901D121PR-G
-2.5V	XC6901D251ER-G	XC6901D251MR-G	XC6901D251PR-G
-2.6V	XC6901D261ER-G	XC6901D261MR-G	XC6901D261PR-G
-3.0V	XC6901D301ER-G	XC6901D301MR-G	XC6901D301PR-G
-3.3V	XC6901D331ER-G	XC6901D331MR-G	XC6901D331PR-G
-4.0V	XC6901D401ER-G	XC6901D401MR-G	XC6901D401PR-G
-4.5V	XC6901D451ER-G	XC6901D451MR-G	XC6901D451PR-G
-5.0V	XC6901D501ER-G	XC6901D501MR-G	XC6901D501PR-G
-6.0V	XC6901D601ER-G	XC6901D601MR-G	XC6901D601PR-G
-12.0V	XC6901DC01ER-G	XC6901DC01MR-G	XC6901DC01PR-G

## ■ ABSOLUTE MAXIMUM RATINGS

GND=0V, Ta=25°C

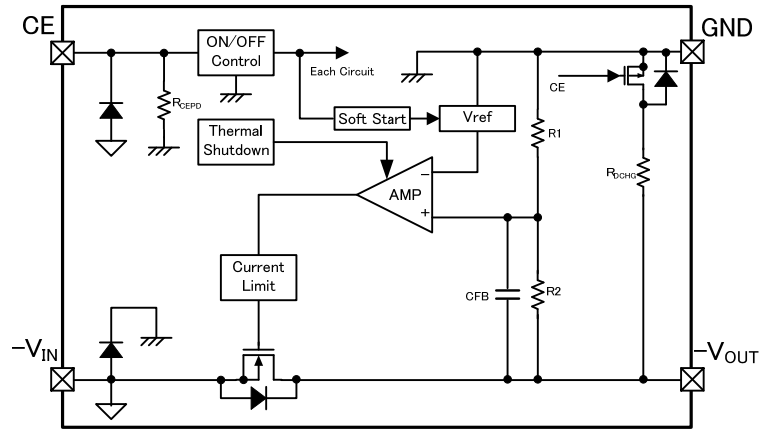
PARAMETER		SYMBOL	RATINGS	UNITS
Input Voltage		$V_{IN}$	GND-18+ $V_{CE}$ ~ GND+0.3	V
Output Current		$I_{OUT}$	500 <sup>(*1)</sup>	mA
Output Voltage		$V_{OUT}$	- $V_{IN}$ -0.3 ~ GND+0.3	V
CE Input Voltage		$V_{CE}$	GND-0.3 ~ $V_{IN}$ +18	V
Power Dissipation	USP-6C	Pd	120	mW
			1000 (PCB mounted) <sup>(*2)</sup>	
	SOT-25		250	
			600 (PCB mounted) <sup>(*2)</sup>	
	SOT-89-5		500	
		1300 (PCB mounted) <sup>(*2)</sup>		
Operating Ambient Temperature		Topr	-40~+85	°C
Storage Temperature		Tstg	-55~+125	°C

(\*1): Please use within the range of  $I_{OUT} \leq Pd / (V_{OUT} - V_{IN})$

(\*2) The power dissipation figure shown is PCB mounted and is for reference only. Please refer to page 24~26 for details.

## ■ BLOCK DIAGRAM

XC6901 Series D type



\*Diodes inside the circuit are an ESD protection diode and a parasitic diode.

## ELECTRICAL CHARACTERISTICS

●XC6901 Series

GND=0V, Ta=25°C

PARAMETER	SYMBOL	CONDITIONS		MIN.	TYP.	MAX.	UNITS	CIRCUIT
Output Voltage	$V_{OUT(E)}$ <sup>(2)</sup>	$I_{OUT}=20mA$	$V_{OUT(T)} < -2.0V$	$\times 1.015$	$V_{OUT(T)}$ <sup>(1)</sup>	$\times 0.985$	V	①
			$V_{OUT(T)} \geq -2.0V$	-0.030		+0.030		
Maximum Output Current <sup>(4)</sup>	$I_{OUTMAX}$	$V_{IN}=V_{OUT(T)}-2.0V$	$V_{OUT(T)} \leq -2.4V$	200	-	-	mA	①
		$V_{IN}=-4.4V$	$V_{OUT(T)} > -2.4V$					
Load Regulation	$\Delta V_{OUT}$	$V_{IN}=V_{OUT(T)}-1.0V$	$V_{OUT(T)} \leq -3.0V$	-	20	60	mV	①
		$V_{IN}=-4.0V$	$V_{OUT(T)} > -3.0V$					
		$1mA \leq I_{OUT} \leq 100mA$						
Dropout Voltage	$V_{dif}$ <sup>(3)</sup>	$I_{OUT}=20mA$		-	E-1 <sup>(5)</sup>		mV	①
Supply Current	$I_{BIAS}$	$V_{IN}=-14.5V, V_{CE}=1.5V, I_{OUT}=0mA$		-	100	200	$\mu A$	①
Stand-by Current	$I_{STB}$	$V_{IN}=-14.5V, V_{CE}=0V, I_{OUT}=0mA$		-	0.01	0.1	$\mu A$	①
Input Line Regulation	$\frac{\Delta V_{OUT}}{(\Delta V_{IN} \cdot V_{OUT})}$	$-14.5V \sim V_{OUT(T)}-1V$	$V_{OUT(T)} \leq -1.4V$	-	0.01	0.20	%V	①
		$-14.5V \sim -2.4V$	$V_{OUT(T)} > -1.4V$					
		$I_{OUT}=20mA$						
Input Voltage	$V_{IN}$			$-16+V_{CE}$	-	-2.4	V	①
Output Voltage Temperature Characteristics	$\frac{\Delta V_{OUT}}{(\Delta T_{opr} \cdot V_{OUT})}$	$I_{OUT}=20mA$ $-40^\circ C \leq T_{opr} \leq 85^\circ C$		-	$\pm 50$	-	ppm/°C	①
Power Supply Rejection Ratio	PSRR	$V_{IN} = \{V_{OUT(T)}-1.0\} + 0.5V_{p-pAC}, I_{OUT}=20mA, f=1kHz$		-	45	-	dB	②
Limit Current	$I_{LIM}$	$V_{IN}=V_{OUT(T)}-2.0V$	$V_{OUT(T)} \leq -2.4V$	210	300	-	mA	①
		$V_{IN}=-4.4V$	$V_{OUT(T)} > -2.4V$					
Short-Circuit Current	$I_{SHORT}$	$V_{IN}=V_{OUT(T)}-2.0V$ Short - $V_{OUT}$ to GND level		-	80	-	mA	①
Detect Thermal Shutdown Temperature	$T_{TSD}$	IC Junction temperature		-	150	-	°C	①
Release Thermal Shutdown Temperature	$T_{TSR}$	IC Junction temperature		-	125	-	°C	①
Hysteresis Width	$T_{HYS}$	$T_{TSD}-T_{TSR}$		-	25	-	°C	①
CE "H" Level Voltage	$V_{CEH}$			1.2	-	3.6	V	①
CE "L" Level Voltage	$V_{CEL}$			GND	-	0.4	V	①
CE "H" Level Current	$I_{CEH}$	$V_{IN}=-12.4V, V_{CE}=3.6V$	XC6901D Series	1.8	4	7	$\mu A$	①
CE "L" Level Current	$I_{CEL}$	$V_{CE}=GND$		-0.1	-	0.1	$\mu A$	①
$C_L$ Discharge Resistor	$R_{DCHG}$	$V_{IN}=-8V, V_{OUT}=-2V, V_{CE}=GND$		0.7	1.2	1.8	k $\Omega$	①
Soft Start Time	$t_{SS}$	$R_L=3k\Omega$ , Rise Time CE="H" to 95% of $V_{OUT(E)}$	$V_{OUT(T)} > -4.0V$	0.15	0.4	1.2	ms	③
			$V_{OUT(T)} \leq -4.0V$	0.3	0.7	2	ms	③

NOTE: Unless otherwise stated regarding input voltage conditions  $V_{CE}=1.5V, GND=0V, V_{IN}=V_{OUT(T)}-1.0V$  or  $-2.4V$  the one which bigger absolute value.

\*1)  $V_{OUT(T)}$ : Nominal output voltage

\*2)  $V_{OUT(E)}$ : Effective output voltage (see the voltage chart)

(ie. The output voltage when " $V_{OUT(T)}-1.0V$ " or " $-2.4V$ " is provided at the  $V_{IN}$  pin while maintaining a certain  $I_{OUT}$  value.

\*3)  $V_{dif} = -\{V_{IN1} - V_{OUT1}\}$

$V_{IN1}$  is the input voltage when  $V_{OUT1}$  appears at the  $V_{OUT}$  pin while input voltage is gradually increased

$V_{OUT1}$  is the voltage equal to 98% of the normal output voltage when amply stabilized  $V_{OUT(T)}-1.0V$  or  $-2.4V$  (the bigger absolute value one) are input at the  $V_{IN}$  pin.

\*4) The maximum current may not be able to flow when thermal shutdown operates, it depends on power dissipation.

\*5) E-1: Refer to dropout voltage chart.

## ■ ELECTRICAL CHARACTERISTICS(Continued)

Dropout Voltage Chart ( $V_{OUT(T)} = -0.9V \sim -5V$ )

NOMINAL OUTPUT VOLTAGE	E-1		NOMINAL OUTPUT VOLTAGE	E-1		NOMINAL OUTPUT VOLTAGE	E-1	
	DROPOUT VOLTAGE			DROPOUT VOLTAGE			DROPOUT VOLTAGE	
	Vdif (mV)			Vdif (mV)			Vdif (mV)	
$V_{OUT(T)}$	TYP.	MAX.	$V_{OUT(T)}$	TYP.	MAX.	$V_{OUT(T)}$	TYP.	MAX.
-0.90	800	1500	-2.85	116	157	-4.80	80	115
-0.95	750	1450	-2.90	114	155	-4.85	80	115
-1.00	700	1400	-2.95	112	153	-4.90	79	115
-1.05	650	1350	-3.00	110	151	-4.95	79	115
-1.10	600	1300	-3.05	109	150	-5.00	78	114
-1.15	550	1250	-3.10	108	148			
-1.20	500	1200	-3.15	107	147			
-1.25	450	1150	-3.20	105	145			
-1.30	400	1100	-3.25	104	144			
-1.35	350	1050	-3.30	102	142			
-1.40	300	1000	-3.35	102	141			
-1.45	270	950	-3.40	101	140			
-1.50	230	900	-3.45	101	139			
-1.55	220	850	-3.50	100	137			
-1.60	210	800	-3.55	99	136			
-1.65	205	750	-3.60	98	135			
-1.70	200	700	-3.65	97	134			
-1.75	195	650	-3.70	95	133			
-1.80	190	600	-3.75	95	132			
-1.85	183	550	-3.80	94	131			
-1.90	176	500	-3.85	94	130			
-1.95	171	450	-3.90	93	129			
-2.00	165	400	-3.95	92	128			
-2.05	161	350	-4.00	91	127			
-2.10	156	300	-4.05	90	126			
-2.15	152	250	-4.10	89	125			
-2.20	148	200	-4.15	89	125			
-2.25	144	187	-4.20	88	124			
-2.30	140	185	-4.25	87	123			
-2.35	138	183	-4.30	86	122			
-2.40	135	181	-4.35	86	122			
-2.45	132	178	-4.40	85	121			
-2.50	129	174	-4.45	85	120			
-2.55	127	172	-4.50	84	119			
-2.60	125	169	-4.55	83	119			
-2.65	123	166	-4.60	82	119			
-2.70	121	163	-4.65	82	118			
-2.75	119	161	-4.70	82	117			
-2.80	117	159	-4.75	81	116			

## ELECTRICAL CHARACTERISTICS(Continued)

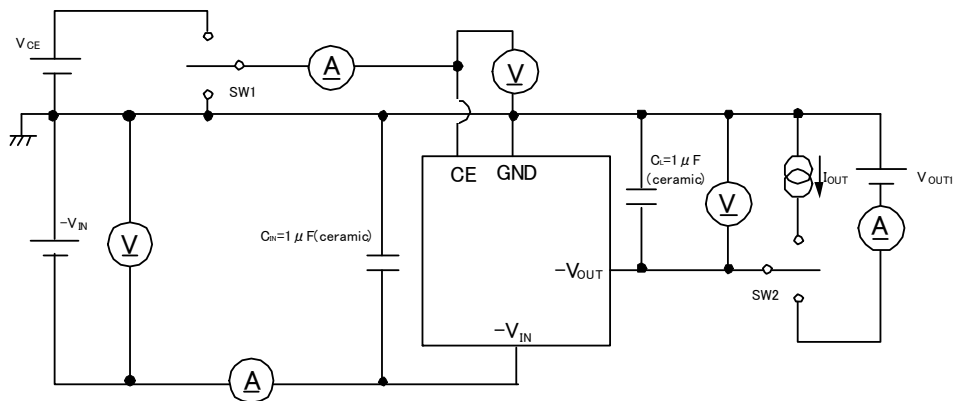
Dropout Voltage Chart ( $V_{OUT(T)} = -5.1V \sim -12V$ )

NOMINAL OUTPUT VOLTAGE	E-1		NOMINAL OUTPUT VOLTAGE	E-1	
	DROPOUT VOLTAGE			DROPOUT VOLTAGE	
	Vdif(mV)			Vdif(mV)	
$V_{OUT(T)}$	TYP.	MAX.	$V_{OUT(T)}$	TYP.	MAX.
-5.1	77	113	-9.0	58	93
-5.2	77	112	-9.1	58	92
-5.3	76	111	-9.2	58	92
-5.4	75	110	-9.3	57	92
-5.5	74	110	-9.4	57	91
-5.6	73	109	-9.5	56	91
-5.7	73	108	-9.6	56	91
-5.8	72	107	-9.7	56	91
-5.9	71	106	-9.8	55	90
-6.0	70	105	-9.9	55	90
-6.1	70	105	-10.0	54	90
-6.2	69	104	-10.1	54	90
-6.3	69	104	-10.2	54	89
-6.4	68	103	-10.3	54	89
-6.5	67	102	-10.4	54	89
-6.6	66	102	-10.5	53	88
-6.7	66	101	-10.6	53	88
-6.8	65	101	-10.7	53	88
-6.9	65	100	-10.8	53	88
-7.0	65	100	-10.9	53	88
-7.1	64	99	-11.0	52	88
-7.2	64	99	-11.1	53	88
-7.3	63	98	-11.2	52	87
-7.4	63	98	-11.3	51	87
-7.5	62	98	-11.4	51	87
-7.6	62	98	-11.5	50	87
-7.7	62	97	-11.6	50	87
-7.8	61	96	-11.7	50	87
-7.9	61	96	-11.8	50	87
-8.0	60	96	-11.9	50	87
-8.1	60	96	-12.0	50	87
-8.2	60	95			
-8.3	60	95			
-8.4	60	94			
-8.5	59	94			
-8.6	59	94			
-8.7	59	94			
-8.8	59	93			
-8.9	59	93			

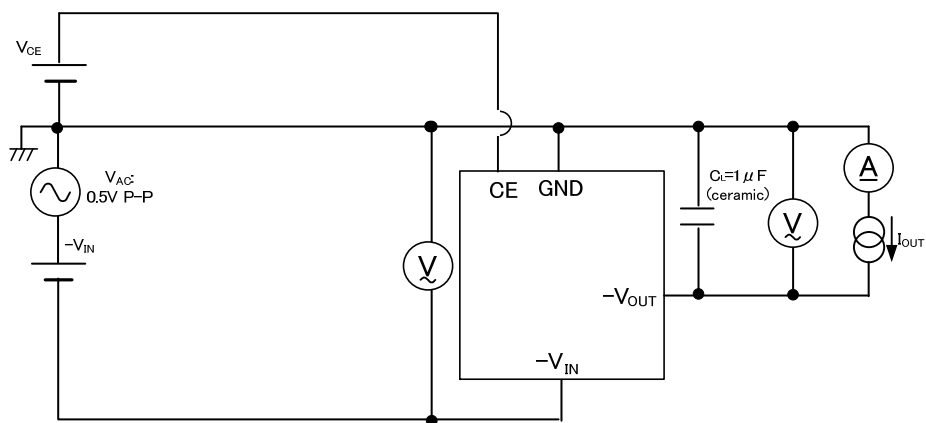


## TEST CIRCUITS

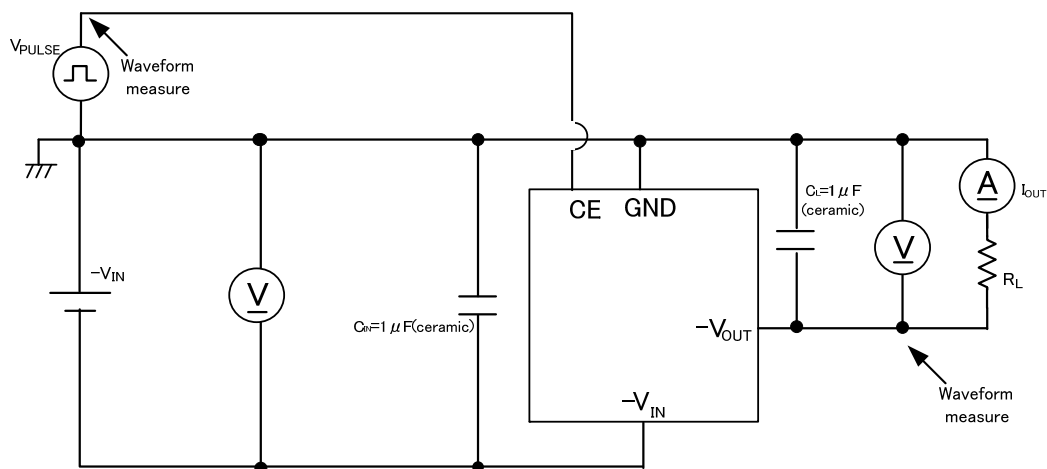
1) CIRCUIT①



2) CIRCUIT②

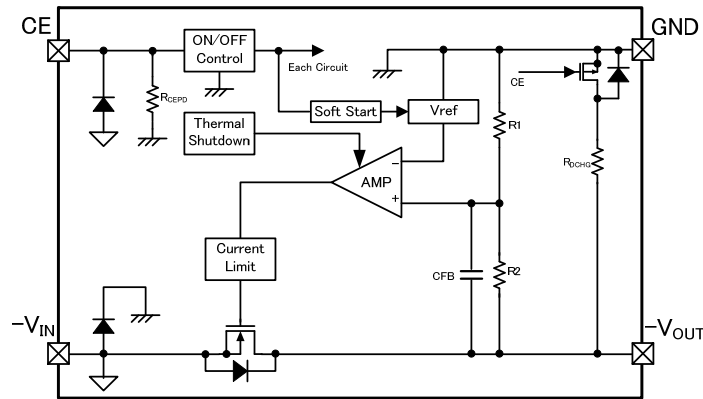


3) CIRCUIT③



## OPERATIONAL EXPLANATION

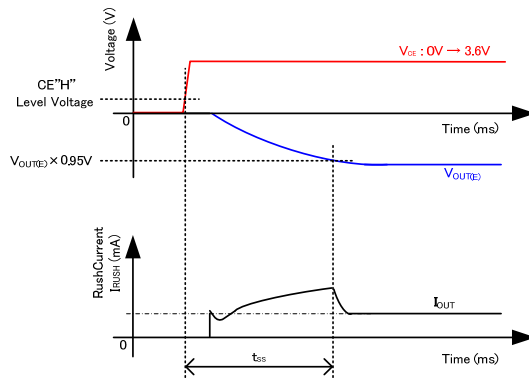
The voltage divided by resistors R1 and R2 is compared with the internal reference voltage based on ground by the error amplifier. The driver transistor tied to the  $-V_{IN}$  pin is then driven by the subsequent output signal. The output voltage at the  $-V_{OUT}$  pin is controlled and stabilized by a system of negative feedback.



### <Soft Start Function>

XC6901 Series includes soft-start circuit. During power start-up, the inrush current from  $-V_{IN}$  pin to  $V_{OUT}$  pin to charge  $C_L$  capacitor can be reduced and it makes the  $V_{IN}$  stable. Soft-start time ( $t_{SS}$ ) is optimized internally.

Figure1 : Soft Start Time and Inrush Current



### <Current Limit, Short-Circuit Protection>

The XC6901 series' fold-back circuit operates as an output current limiter and a short protection circuit for the output pin. When the output current reaches the current limit level, output voltage drops with the decrease of the output current. There are no parasitic diode between the  $-V_{OUT}$  pin and GND pin. The minimized short-circuit current is maintained even if the  $-V_{OUT}$  pin voltage is pulled up toward positive.

### <Thermal Shutdown>

The XC6901 Series has an internal thermal Shutdown(TSD) circuit for protection against overheating.

When the junction temperature reaches the detection temperature, the driver transistor is forcibly turned off. When the junction temperature falls to the release temperature with the driver transistor still in the off state, the driver transistor turns on (automatic recovery) and restarts regulator operation.

### <CE Pin>

The XC6901 Series is able to shut down the regulator circuit using the CE pin signal. CE pin can be controlled with positive voltage due to P-channel transistor source input (Gate is grounded). A current flow of a few micro amperes. The regulator is turned on when CE input voltage is positive, the regulator is turned off when CE input is GND.

When CE pin is open, IC is turned OFF, due to the built-in Pull-down resistor. When the IC is turned OFF with low input voltage to the CE pin,  $-V_{OUT}$  pin voltage goes into GND level by R1, R2 and CL discharge resistance( $R_{DCHG}$ ).

## ■ OPERATIONAL EXPLANATION(Continued)

### <C<sub>L</sub> High Speed Discharge>

The XC6901D type is capable of high-speed discharge of the charge that collects on the output capacitor (C<sub>L</sub> below). This is accomplished by the P-channel MOSFET and C<sub>L</sub> discharge resistance connected between the -V<sub>OUT</sub> and GND pins in the block diagram, and takes place when the L-level signal (IC internal circuit shutdown signal) of the CE pin is input so that it could avoid malfunction.

The C<sub>L</sub> discharge time is determined by this C<sub>L</sub> discharge resistance and C<sub>L</sub>. Letting the time constant of the C<sub>L</sub> discharge resistance R<sub>DCHG</sub> and C<sub>L</sub> be  $\tau$  ( $\tau = C \times R$ ), the output voltage after discharge by the P-channel MOSFET can be obtained from the CR discharge equation below. Please be noted that R<sub>DCHG</sub> varies with supply voltage and V<sub>DS</sub>(drain-source voltage) since it consists of P-channel MOSFET.

$$t = \tau \ln (V_{OUT(E)} / V)$$

V: Output voltage during discharge

V<sub>OUT(E)</sub>: Output voltage

t: Discharge time

$\tau$ : C<sub>L</sub> auto-discharge resistance R<sub>DCHG</sub> × C<sub>L</sub> Output capacitor value C<sub>L</sub>

### <Low ESR Capacitor>

With the XC6901 series, a stable output voltage is achievable even if used with low ESR capacitors, as a phase compensation circuit is built-in. The output capacitor (C<sub>L</sub>) should be connected as close to -V<sub>OUT</sub> pin and GND pin to obtain stable phase compensation. Values required for the phase compensation are as the table below.

For a stable power input, please connect an input capacitor (C<sub>IN</sub>) near power supply. In order to ensure the stable phase compensation while avoiding run-out of values, please use the capacitor (C<sub>IN</sub>, C<sub>L</sub>) which does not depend on bias or temperature too much. The table below shows recommended values of C<sub>IN</sub>, C<sub>L</sub> for all environment conditions.

CHART 1 : Recommended Values of C<sub>IN</sub>, C<sub>L</sub> (MIN.)

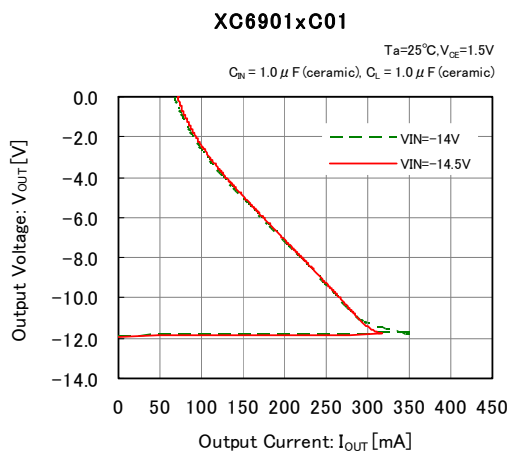
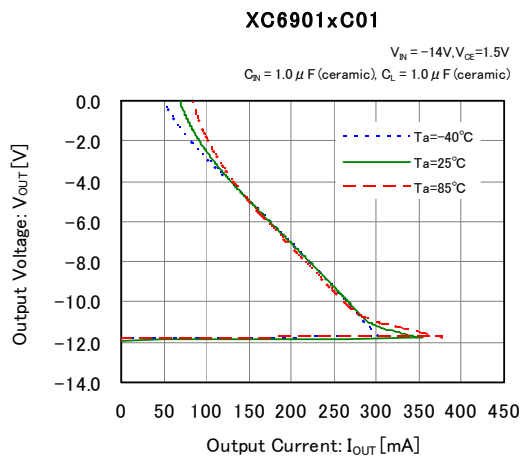
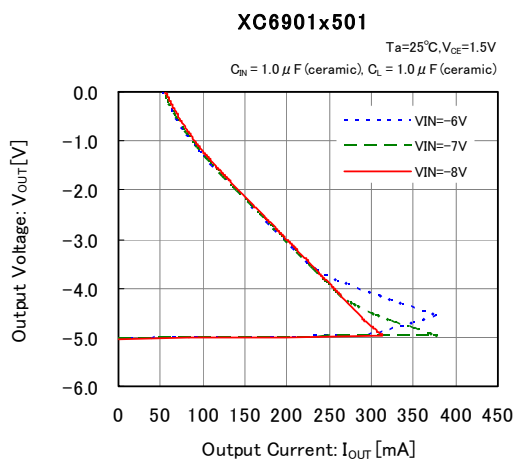
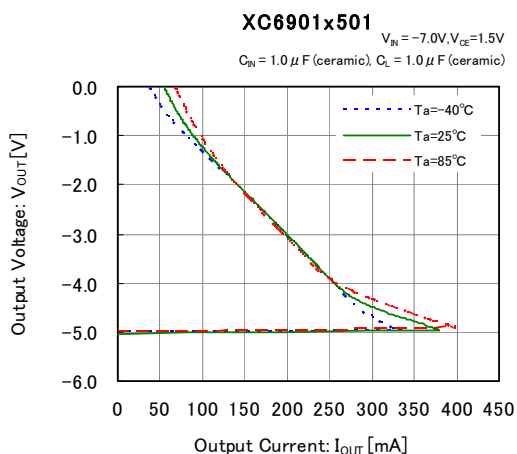
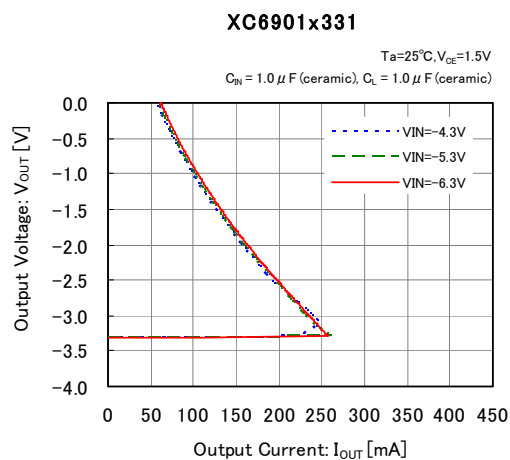
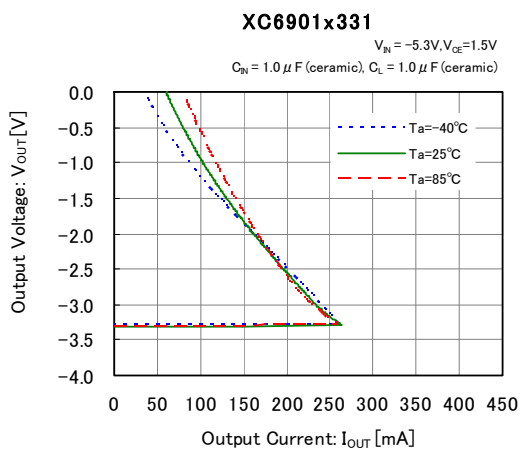
OUTPUT VOLTAGE RANGE	INPUT CAPACITOR	OUTPUT CAPACITOR
V <sub>OUT(T)</sub>	C <sub>IN</sub>	C <sub>L</sub>
-0.9V~-12V	1.0 μF~	1.0 μF~100 μF

## ■ NOTE ON USE

- 1) For temporary, transitional voltage drop or voltage rising phenomenon. The IC is liable to malfunction should the ratings be exceeded.
- 2) Where wiring impedance is high, operations may become unstable due to noise and/or phase lag depending on output current. Please enforce wiring  $-V_{IN}$  and GND.
- 3) Please wire the  $C_{IN}$  and  $C_L$  as close to the IC as possible.
- 4) Capacitances of these capacitors ( $C_{IN}$ ,  $C_L$ ) are decreased by the influences of bias voltage and ambient temperature. Care shall be taken for capacitor selection to ensure stability of phase compensation from the point of ESR influence.
- 5) Torex places an importance on improving our products and its reliability. However, by any possibility, we would request user fail-safe design and post-aging treatment on system or equipment.

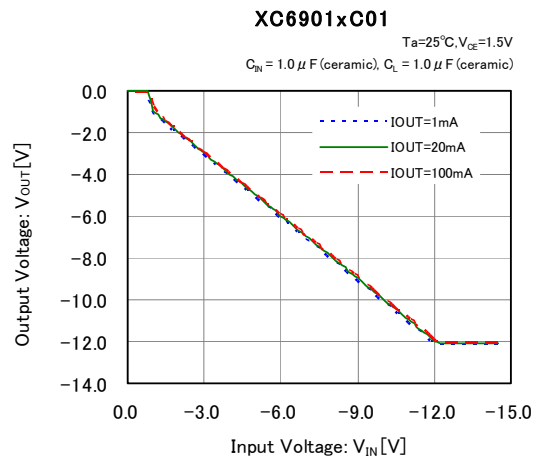
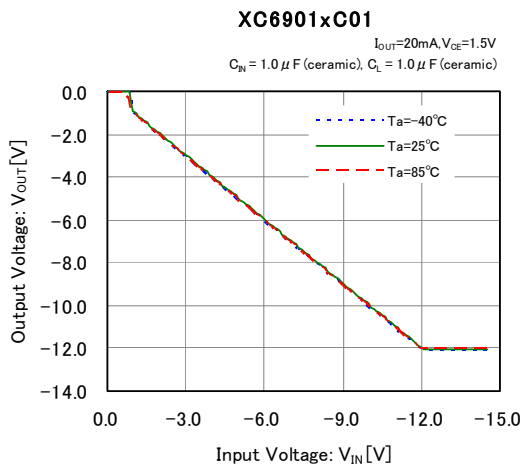
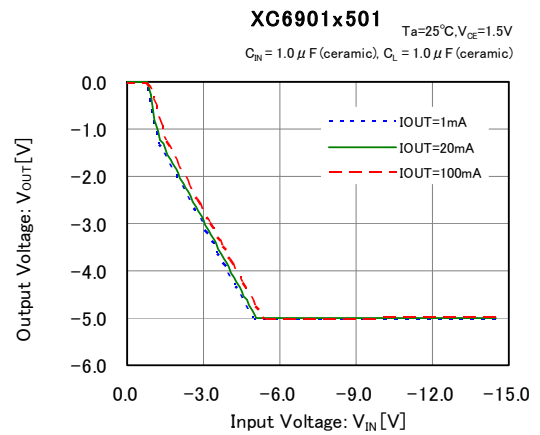
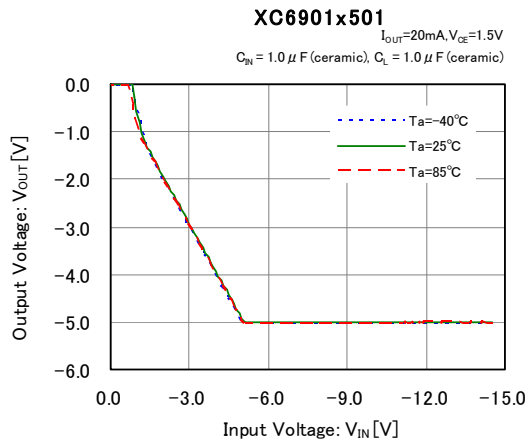
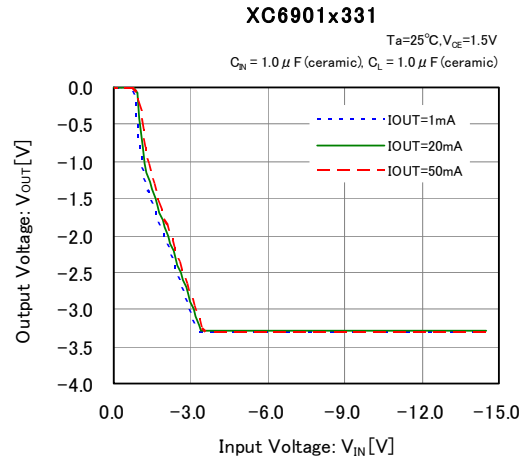
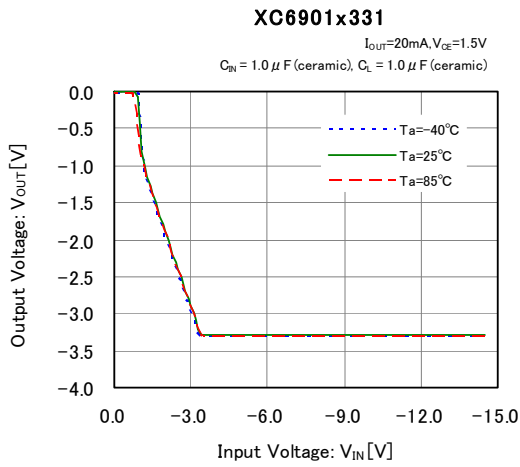
# TYPICAL PERFORMANCE CHARACTERISTICS

## (1) Output Voltage vs. Output Current



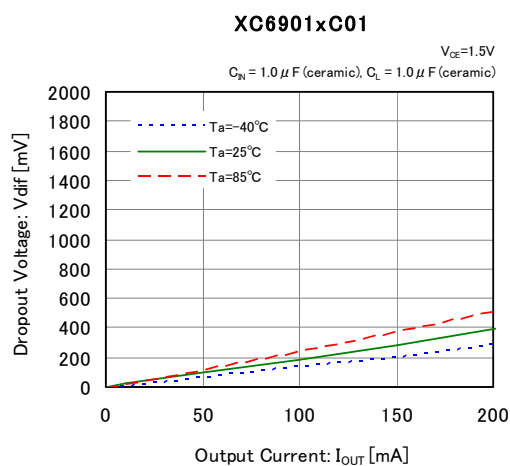
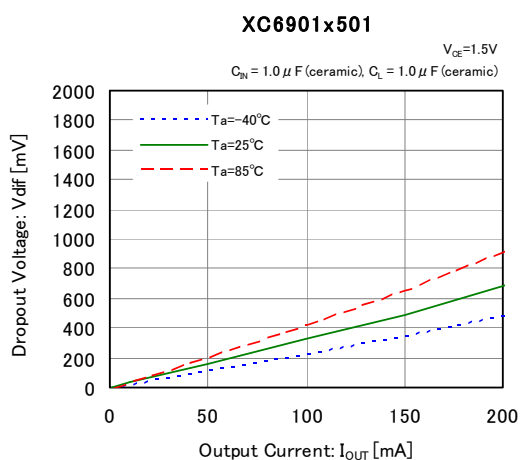
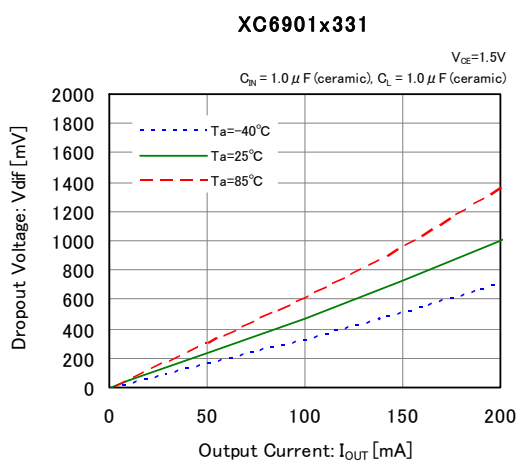
## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

### (2) Output Voltage vs. Input Voltage

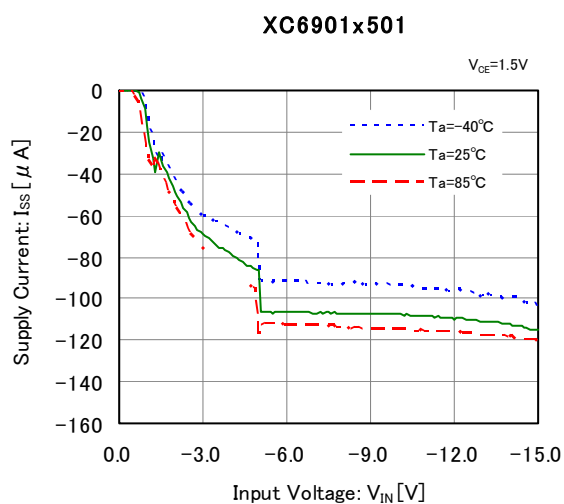
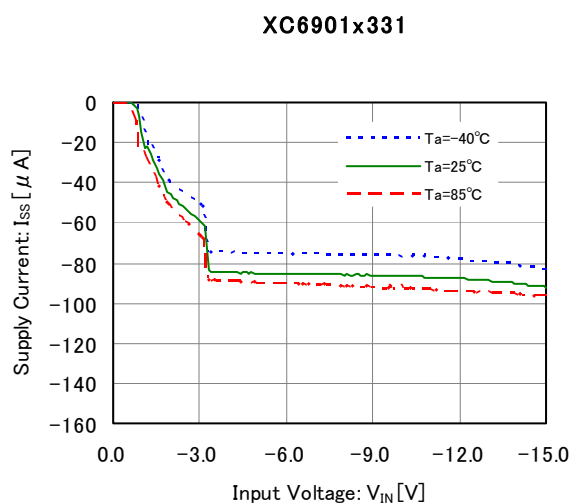


## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

### (3) Dropout Voltage vs. Output Current

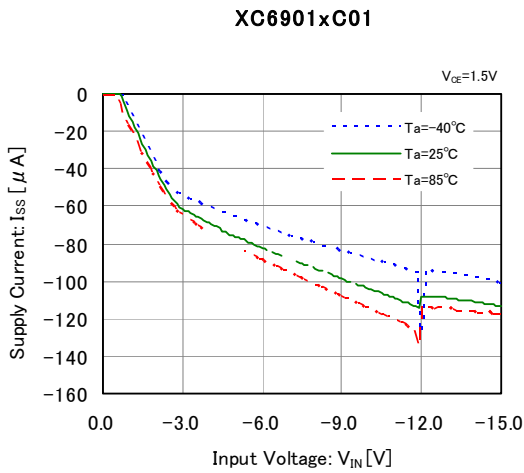


### (4) Supply Current vs. Input Voltage

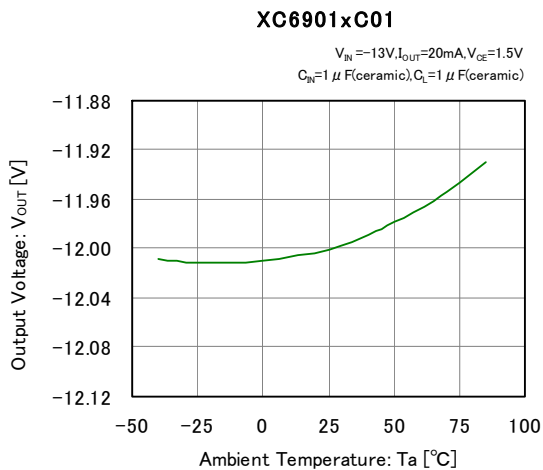
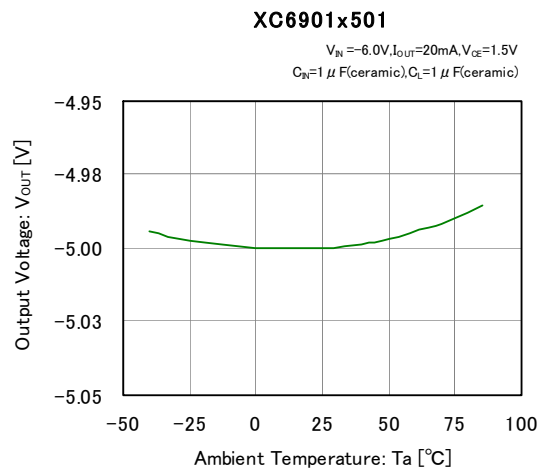
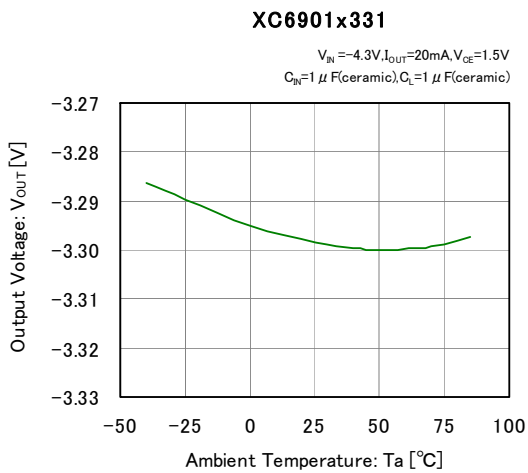


## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

### (4) Supply Current vs. Input Voltage (Continued)



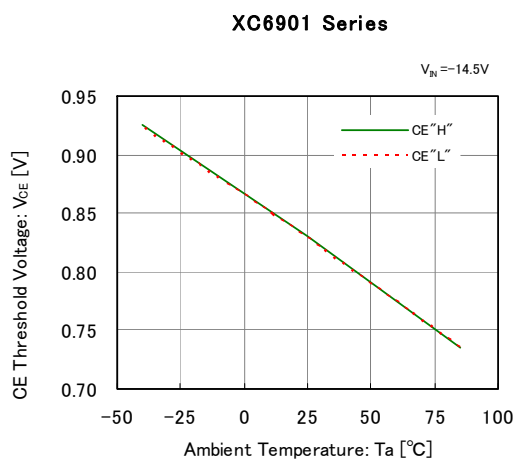
### (5) Output Voltage vs. Ambient Temperature



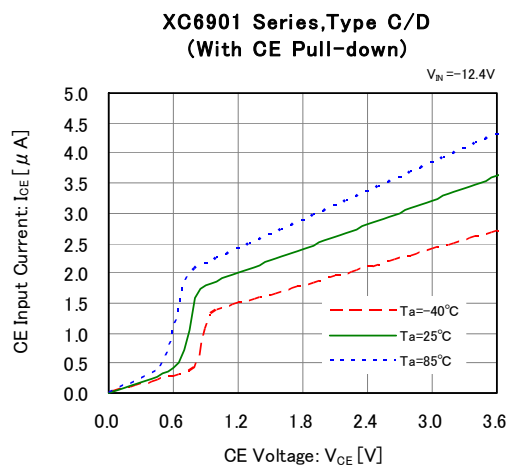
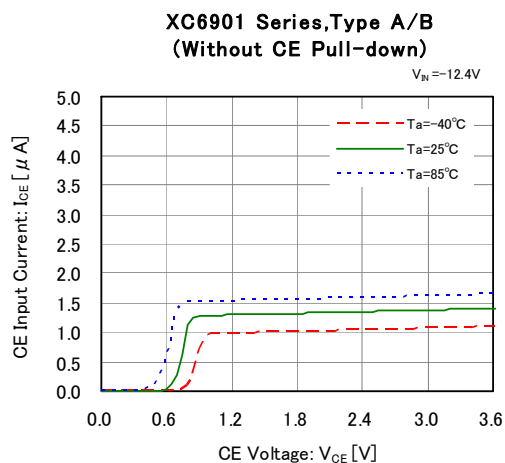


## ■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

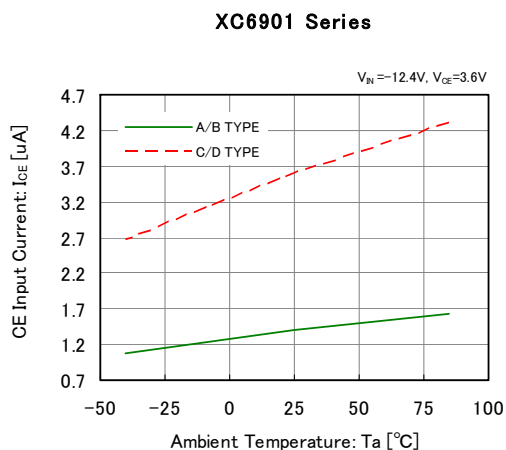
(6) CE Pin Threshold Voltage vs Ambient Temperature



(7) CE Input Current vs CE Voltage

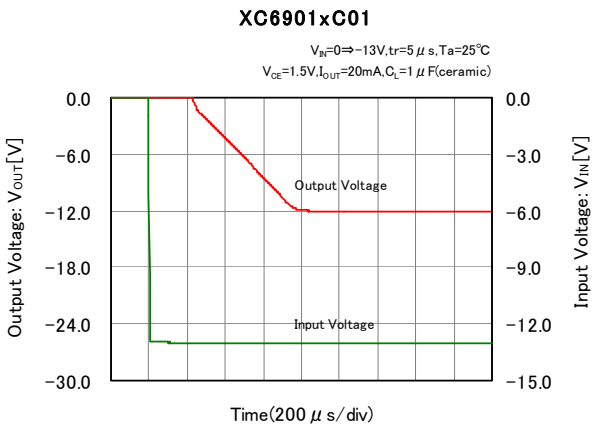
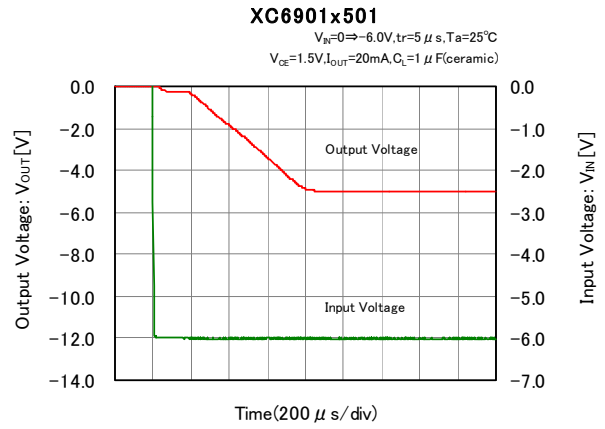
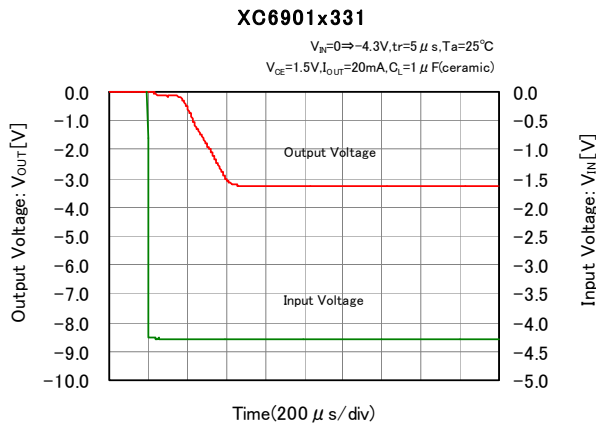


(8) CE Input Current vs Ambient Temperature

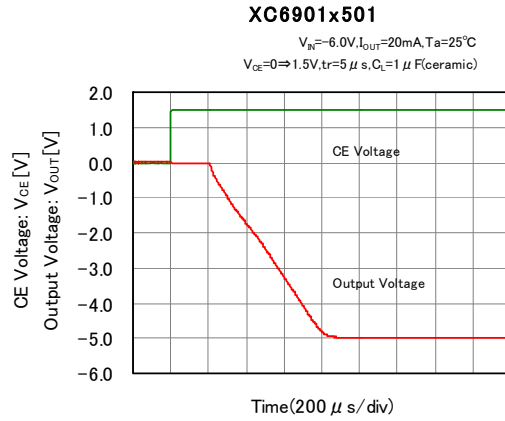
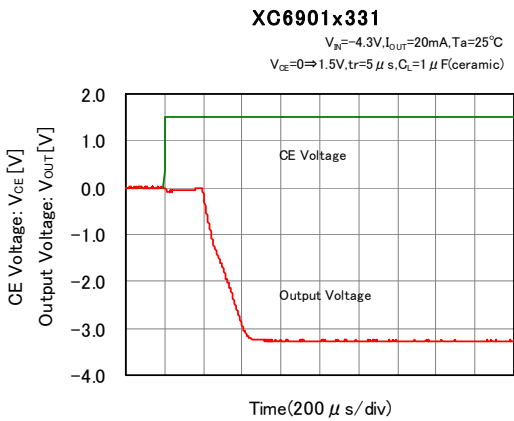


## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

### (9) Input Rising Response Time

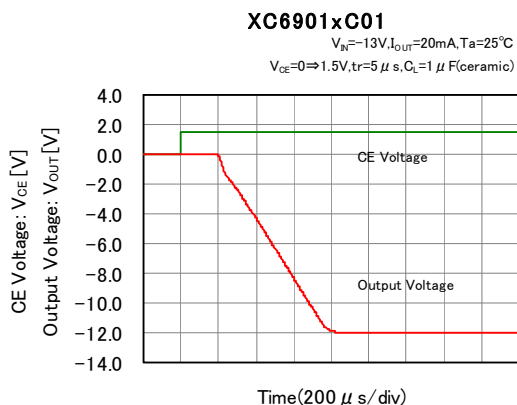


### (10) CE Rising Response Time

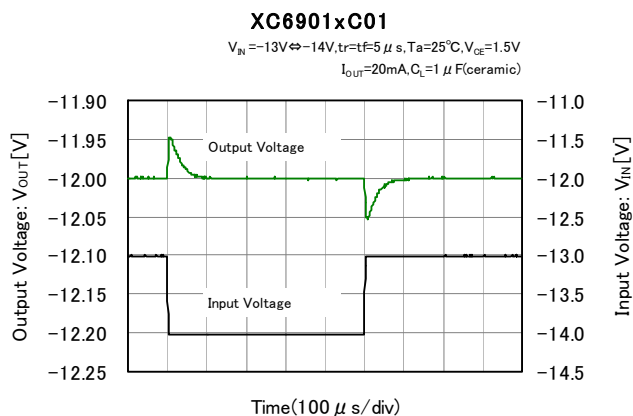
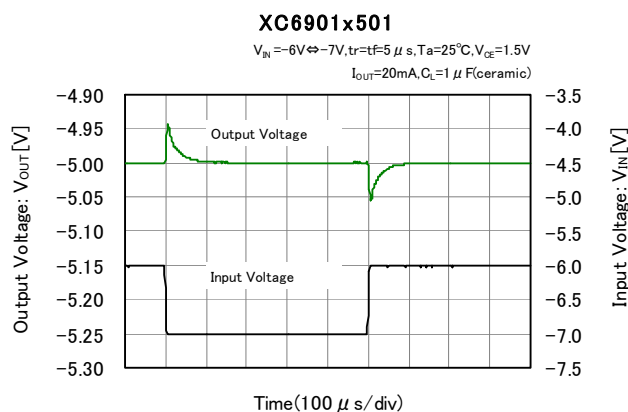
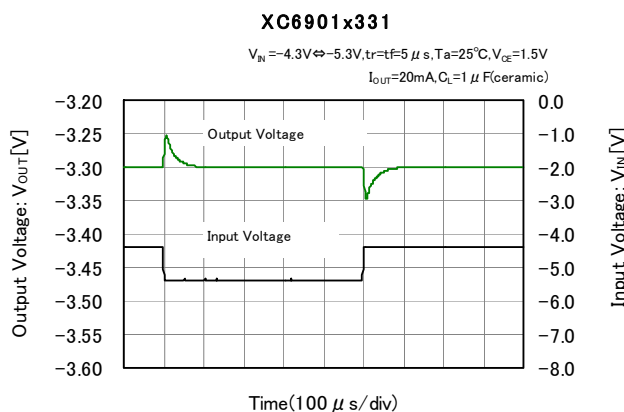


## ■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

### (10) CE Rising Response Time (Continued)



### (11) Input Transient Response

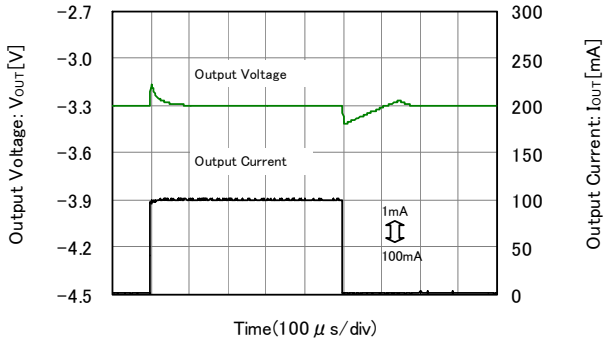


## TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

### (12) Load Transient Response

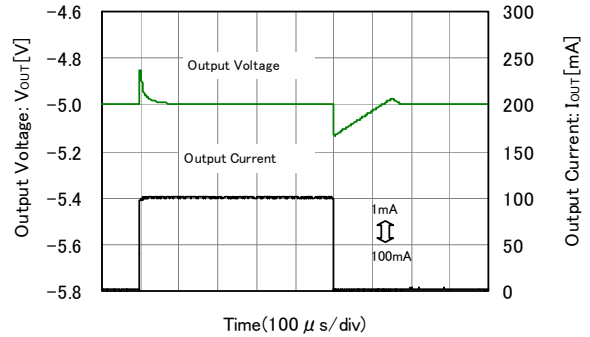
**XC6901x331**

$I_{OUT} = 1 \leftrightarrow 100\text{mA}$ ,  $t_r = t_f = 5 \mu\text{s}$ ,  $T_a = 25^\circ\text{C}$ ,  $V_{CE} = 1.5\text{V}$   
 $V_N = -4.3\text{V}$ ,  $C_N = 1 \mu\text{F}$  (ceramic),  $C_L = 1 \mu\text{F}$  (ceramic)



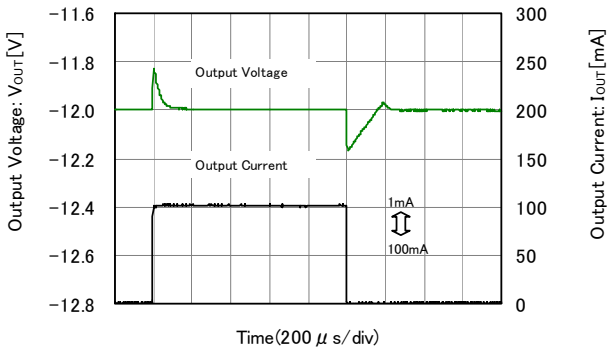
**XC6901x501**

$I_{OUT} = 1 \leftrightarrow 100\text{mA}$ ,  $t_r = t_f = 5 \mu\text{s}$ ,  $T_a = 25^\circ\text{C}$ ,  $V_{CE} = 1.5\text{V}$   
 $V_N = -6\text{V}$ ,  $C_N = 1 \mu\text{F}$  (ceramic),  $C_L = 1 \mu\text{F}$  (ceramic)



**XC6901xC01**

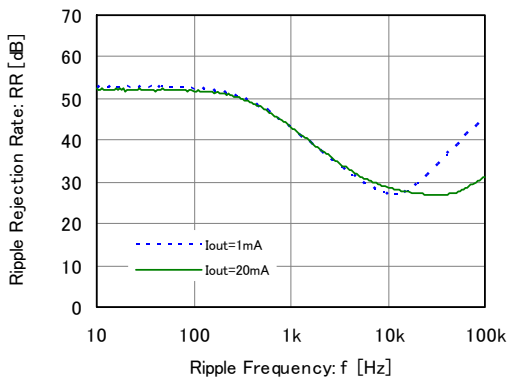
$I_{OUT} = 1 \leftrightarrow 100\text{mA}$ ,  $t_r = t_f = 5 \mu\text{s}$ ,  $T_a = 25^\circ\text{C}$ ,  $V_{CE} = 1.5\text{V}$   
 $V_N = -13\text{V}$ ,  $C_N = 1 \mu\text{F}$  (ceramic),  $C_L = 1 \mu\text{F}$  (ceramic)



### (13) Ripple Rejection Rate

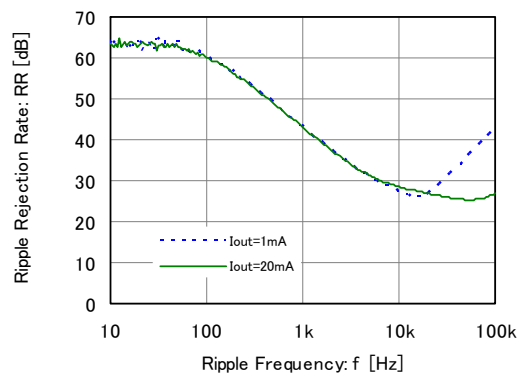
**XC6901x331**

$T_a = 25^\circ\text{C}$ ,  $V_N = -4.3\text{V} + 0.5V_{F-PAC}$   
 $V_{CE} = 1.5\text{V}$ ,  $C_L = 1 \mu\text{F}$  (ceramic)



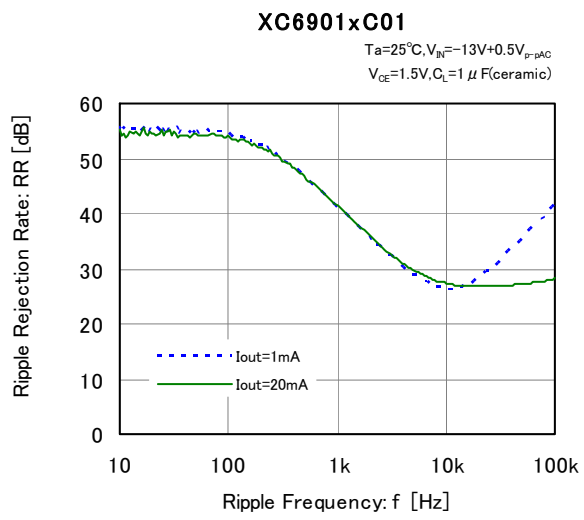
**XC6901x501**

$T_a = 25^\circ\text{C}$ ,  $V_N = -6\text{V} + 0.5V_{F-PAC}$   
 $V_{CE} = 1.5\text{V}$ ,  $C_L = 1 \mu\text{F}$  (ceramic)



## ■ TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

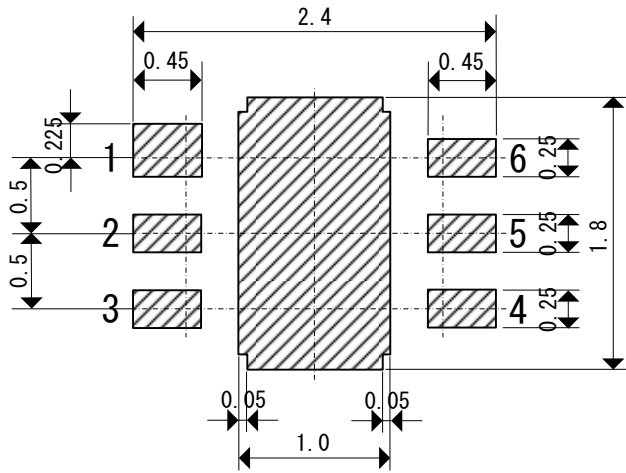
(13) Ripple Rejection Rate (Continued)



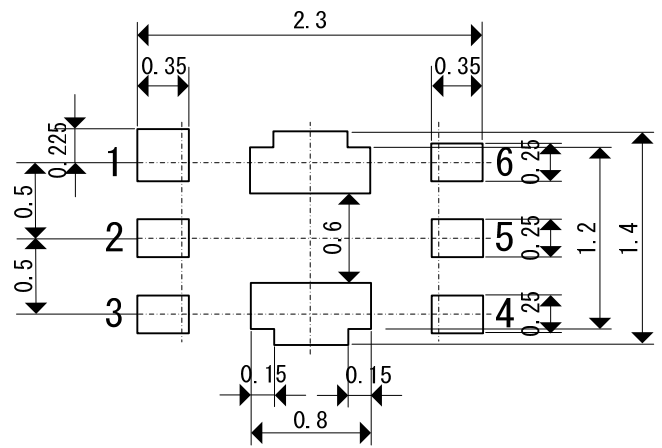


**PACKAGING INFORMATION (Continued)**

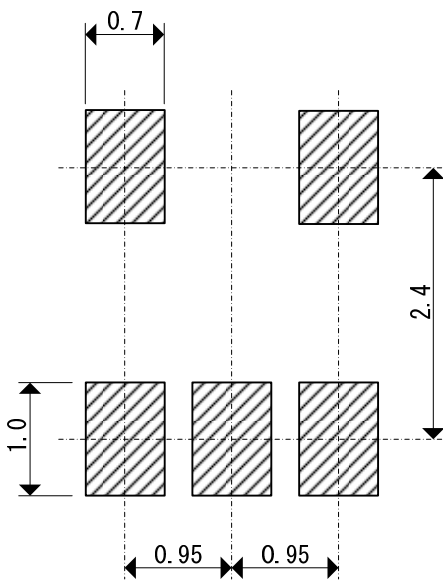
● USP-6C Reference Pattern Layout



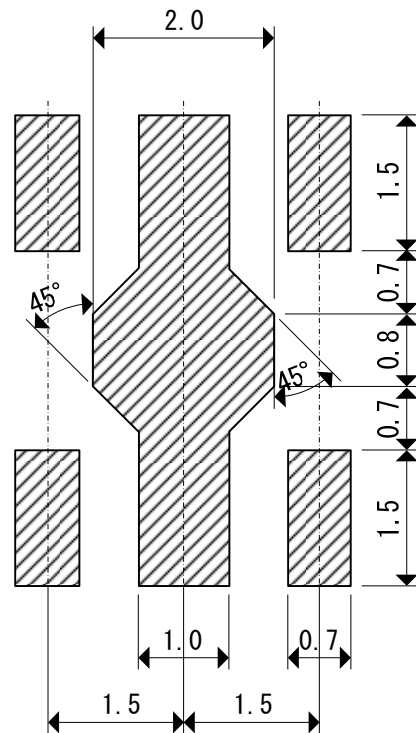
● USP-6C Reference Metal Mask Design



● SOT-25 Reference Pattern Layout



● SOT-89-5 Reference Pattern Layout



## PACKAGING INFORMATION (Continued)

### ● SOT-25 Power Dissipation

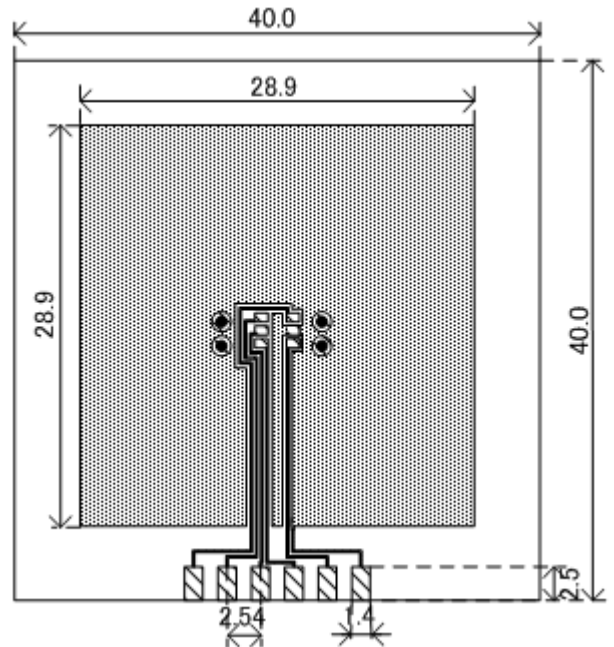
Power dissipation data for the SOT-25 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

#### 1. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm<sup>2</sup> in one side)  
Copper (Cu) traces occupy 50% of the board area  
In top and back faces  
Package heat-sink is tied to the copper traces  
(Board of SOT-26 is used.)
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

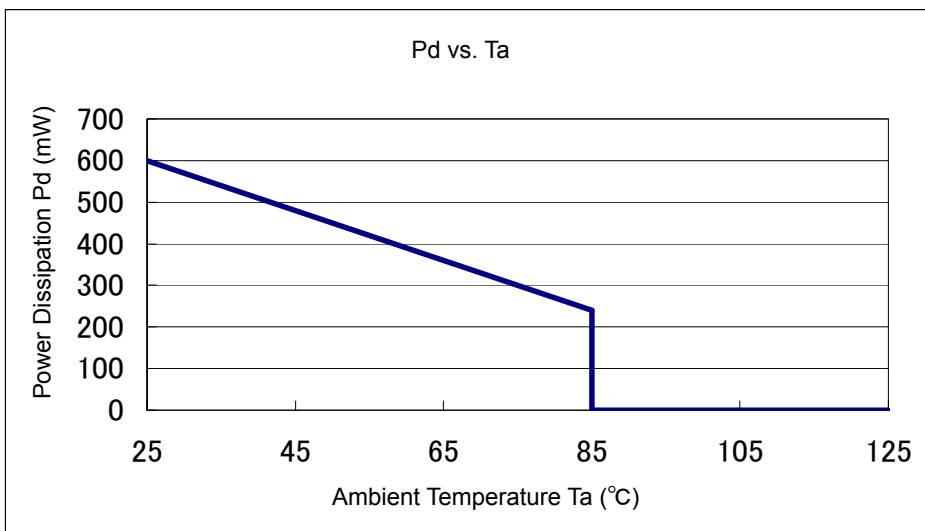


#### 2. Power Dissipation vs. Ambient temperature

Evaluation Board (Unit: mm)

Board Mount ( $T_j \text{ max} = 125^\circ\text{C}$ )

Ambient Temperature ( $^\circ\text{C}$ )	Power Dissipation Pd (mW)	Thermal Resistance ( $^\circ\text{C}/\text{W}$ )
25	600	166.67
85	240	





## ■ PACKAGING INFORMATION (Continued)

### ● SOT-89-5 Power Dissipation

Power dissipation data for the SOT-89-5 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

#### 2. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board: Dimensions 40 x 40 mm (1600 mm<sup>2</sup> in one side)

Copper (Cu) traces occupy 50% of the board area

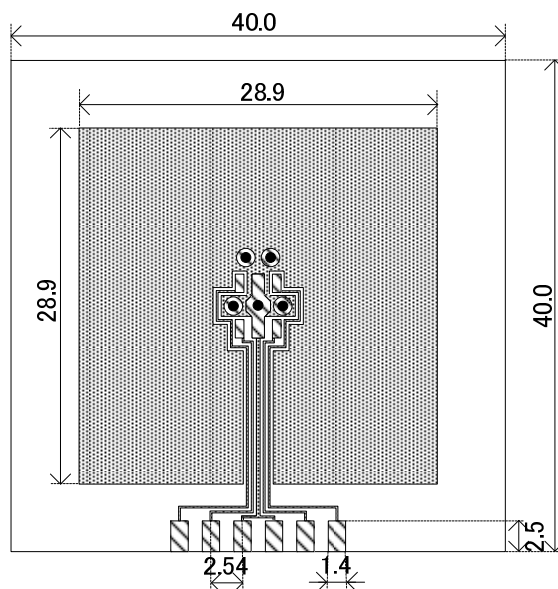
In top and back faces

Package heat-sink is tied to the copper traces

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: 5 x 0.8 Diameter

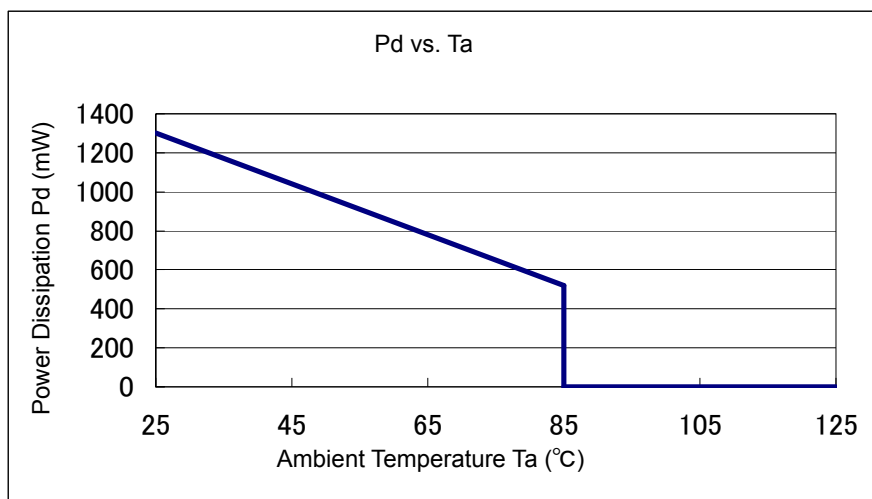


Evaluation Board (Unit: mm)

#### 2. Power Dissipation vs. Ambient temperature

Board Mount ( $T_j \text{ max} = 125^\circ\text{C}$ )

Ambient Temperature ( $^\circ\text{C}$ )	Power Dissipation Pd (mW)	Thermal Resistance ( $^\circ\text{C}/\text{W}$ )
25	1300	76.92
85	520	



## PACKAGING INFORMATION (Continued)

- USP-6C Power Dissipation

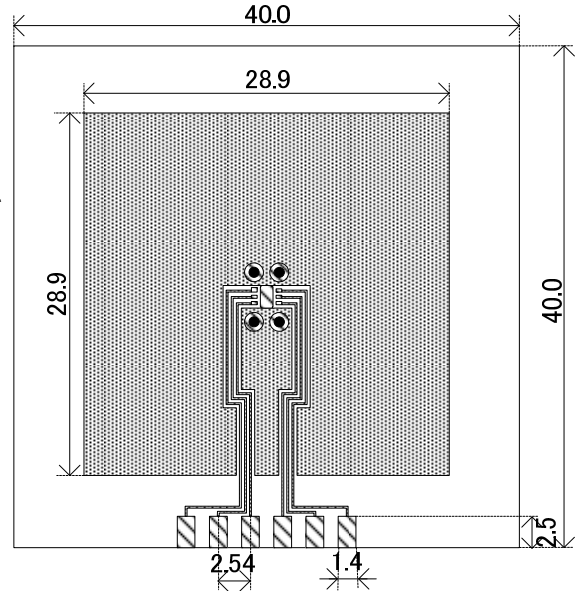
Power dissipation data for the USP-6C is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

### 3. Measurement Condition (Reference data)

- Condition: Mount on a board
- Ambient: Natural convection
- Soldering: Lead (Pb) free
- Board: Dimensions 40 x 40 mm (1600 mm<sup>2</sup> in one side)  
Copper (Cu) traces occupy 50% of the board area  
In top and back faces  
Package heat-sink is tied to the copper traces
- Material: Glass Epoxy (FR-4)
- Thickness: 1.6 mm
- Through-hole: 4 x 0.8 Diameter

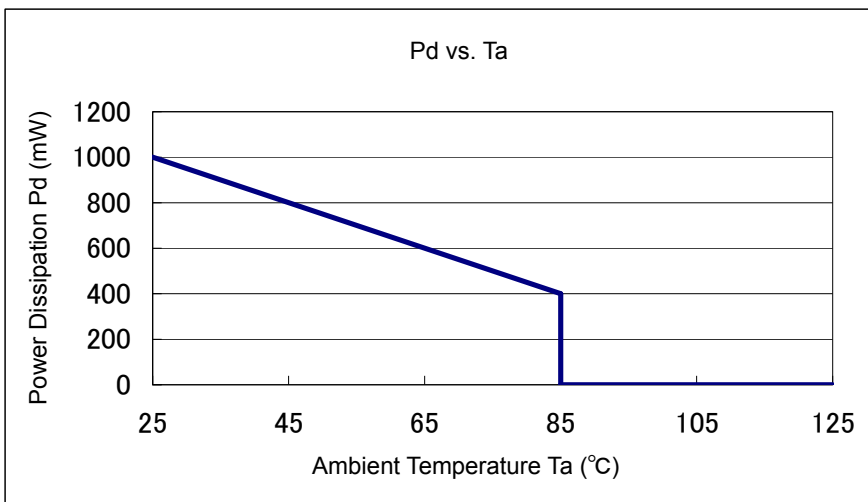


### 2. Power Dissipation vs. Ambient temperature

Board Mount ( $T_j \text{ max} = 125^\circ\text{C}$ )

Evaluation Board (Unit: mm)

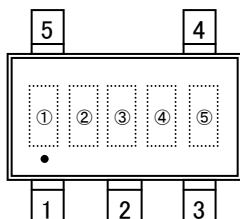
Ambient Temperature (°C)	Power Dissipation Pd (mW)	Thermal Resistance (°C/W)
25	1000	100.00
85	400	



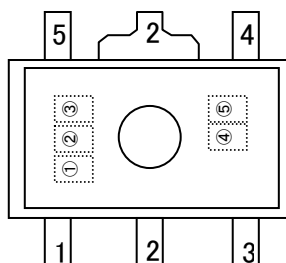
## MARKING RULE

### SOT-25(Under dot)

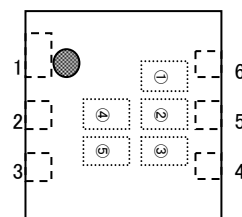
※A dot is marked below the mark of ①



### SOT89-5



### USP-6C



① represents product series

MARK	PRODUCT SERIES
F	XC6901*****_G

② represents output voltage range and product types

MARK	OUTPUT VOLTAGE (V)	TYPE	PRODUCT SERIES
R	-0.9 ~ -3.8	D	XC6901D091**-G ~ XC6901D381**-G
S	-3.9 ~ -6.8		XC6901D391**-G ~ XC6901D681**-G
T	-6.9 ~ -9.8		XC6901D691**-G ~ XC6901D981**-G
U	-9.9 ~ -12.0		XC6901D991**-G ~ XC6901DC01**-G

③ represents output voltage

MARK	OUTPUT VOLTAGE (V)				MARK	OUTPUT VOLTAGE (V)				MARK	OUTPUT VOLTAGE (V)			
0	-0.9	-3.9	-6.9	-9.9	A	-1.9	-4.9	-7.9	-10.9	N	-2.9	-5.9	-8.9	-11.9
1	-1.0	-4.0	-7.0	-10.0	B	-2.0	-5.0	-8.0	-11.0	P	-3.0	-6.0	-9.0	-12.0
2	-1.1	-4.1	-7.1	-10.1	C	-2.1	-5.1	-8.1	-11.1	R	-3.1	-6.1	-9.1	-
3	-1.2	-4.2	-7.2	-10.2	D	-2.2	-5.2	-8.2	-11.2	S	-3.2	-6.2	-9.2	-
4	-1.3	-4.3	-7.3	-10.3	E	-2.3	-5.3	-8.3	-11.3	T	-3.3	-6.3	-9.3	-
5	-1.4	-4.4	-7.4	-10.4	F	-2.4	-5.4	-8.4	-11.4	U	-3.4	-6.4	-9.4	-
6	-1.5	-4.5	-7.5	-10.5	H	-2.5	-5.5	-8.5	-11.5	V	-3.5	-6.5	-9.5	-
7	-1.6	-4.6	-7.6	-10.6	K	-2.6	-5.6	-8.6	-11.6	X	-3.6	-6.6	-9.6	-
8	-1.7	-4.7	-7.7	-10.7	L	-2.7	-5.7	-8.7	-11.7	Y	-3.7	-6.7	-9.7	-
9	-1.8	-4.8	-7.8	-10.8	M	-2.8	-5.8	-8.8	-11.8	Z	-3.8	-6.8	-9.8	-

④,⑤ represents production lot number

01~09, 0A~0Z, 11~9Z, A1~A9, AA~AZ, B1~ZZ repeated

(G, I, J, O, Q, W excluded)

\*No character inversion used.